DGG, DGV, OR DL PACKAGE

(TOP VIEW)

SCES095D-MARCH 1997-REVISED SEPTEMBER 2004

FEATURES

- Member of the Texas Instruments Widebus™
 Family
- EPIC[™] (Enhanced-Performance Implanted CMOS) Submicron Process
- Checks Parity
- Able to Cascade With a Second SN74ALVCH16903
- ESD Protection Exceeds 2000 V Per MIL-STD-883, Method 3015; Exceeds 200 V Using Machine Model (C = 200 pF, R = 0)
- Latch-Up Performance Exceeds 250 mA Per JESD 17
- Bus Hold on Data Inputs Eliminates the Need for External Pullup/Pulldown Resistors
- Package Options Include Plastic 300-mil Shrink Small-Outline (DL), Thin Shrink Small-Outline (DGG), and Thin Very Small-Outline (DGV) Packages

DESCRIPTION

This 12-bit universal bus driver is designed for 2.3-V to 3.6-V V_{CC} operation.

The SN74ALVCH16903 has dual outputs and can operate as a buffer or an edge-triggered register. In both modes, parity is checked on APAR, which arrives one cycle after the data to which it applies. The YERR output, which is produced one cycle after APAR, is open drain.

MODE selects one of the two data paths. When MODE is low, the device operates as an edge-triggered register. On the positive transition of the clock (CLK) input and when the clock-enable

56**∏** CLK OE [1Y1 🛮 2 55**∏** 1A 1Y2 **∏**3 54 11A/YERREN GND 4 53 GND 52 11Y1 2Y1 2Y2 **[**]6 51 1 11Y2 50 V_{CC} V_{CC} L 3Y1 **[**]8 49**∏** 2A 3Y2 **[**]9 48 3A 4Y1 110 47 **1** 4A 46∏ GND GND LI11 4Y2 112 45 12A 5Y1 **∏**13 44**∏** 12Y1 43 12Y2 5Y2 114 6Y1 []15 42**|**1 5A 6Y2 116 41 6A 7Y1 17 40 7A 39 T GND GND 118 7Y2 []19 38 APAR 8Y1 [**1**20 37**∏** 8A 8Y2 **1**21 36 YERR V_{CC} **□**22 35 V_{CC} 9Y1 **[**]23 34 9A 33 MODE 9Y2 **∐**24 GND 25 32 GND 10Y1 **1**26 31 T 10A 10Y2 **1**27 30 PARI/O PAROE 28 29 CLKEN

(CLKEN) input is low, data set up at the A inputs is stored in the internal registers. On the positive transition of CLK and when CLKEN is high, only data set up at the 9A–12A inputs is stored in their internal registers. When MODE is high, the device operates as a buffer and data at the A inputs passes directly to the outputs. 11A/YERREN serves a dual purpose; it acts as a normal data bit and also enables YERR data to be clocked into the YERR output register.

When used as a single device, parity output enable (PAROE) must be tied high; when parity input/output (PARI/O) is low, even parity is selected and when PARI/O is high, odd parity is selected. When used in pairs and PAROE is low, the parity sum is output on PARI/O for cascading to the second SN74ALVCH16903. When used in pairs and PAROE is high, PARI/O accepts a partial parity sum from the first SN74ALVCH16903.

A buffered output-enable (\overline{OE}) input can be used to place the 24 outputs and \overline{YERR} in either a normal logic state (high or low logic levels) or a high-impedance state. In the high-impedance state, the outputs neither load nor drive the bus lines significantly. The high-impedance state and increased drive provide the capability to drive bus lines without need for interface or pullup components.

 $\overline{\text{OE}}$ does not affect the internal operation of the device. Old data can be retained or new data can be entered while the outputs are in the high-impedance state.

Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.

Widebus, EPIC are trademarks of Texas Instruments.



DESCRIPTION (CONTINUED)

To ensure the high-impedance state during power up or power down, $\overline{\text{OE}}$ should be tied to V_{CC} through a pullup resistor; the minimum value of the resistor is determined by the current-sinking capability of the driver.

Active bus-hold circuitry is provided to hold unused or floating data inputs at a valid logic level.

The SN74ALVCH16903 is characterized for operation from 0°C to 70°C.

FUNCTION TABLES

FUNCTION

		INPUTS		OUT	PUTS	
ŌĒ	MODE	CLKEN	CLK A		1Yn ⁽¹⁾ –8Yn ⁽¹⁾	9Yn ⁽¹⁾ –12Yn ⁽¹⁾
L	L	L	↑	Н	Н	Н
L	L	L	\uparrow	L	L	L
L	L	Н	\uparrow	Н	Y_0	Н
L	L	Н	\uparrow	L	Y_0	L
L	Н	Χ	Χ	Н	Н	Н
L	Н	Χ	Χ	L	L	L
Н	Χ	X	Χ	Χ	Z	Z

(1) n = 1 or 2

PARITY FUNCTION

		INF	PUTS			OUTPUT
ŌĒ	PAROE (1)	11A/YERREN ⁽²⁾	PARI/O	Σ OF INPUTS 1A-10A = H	APAR	YERR
L	Н	L	L	0, 2, 4, 6, 8, 10	L	Н
L	Н	L	L	1, 3, 5, 7, 9	L	L
L	Н	L	L	0, 2, 4, 6, 8, 10	Н	L
L	Н	L	L	1, 3, 5, 7, 9	Н	Н
L	Н	L	Н	0, 2, 4, 6, 8, 10	L	L
L	Н	L	Н	1, 3, 5, 7, 9	L	Н
L	Н	L	Н	0, 2, 4, 6, 8, 10	Н	Н
L	Н	L	Н	1, 3, 5, 7, 9	Н	L
Н	Х	X	Х	X	Х	Н
L	Х	Н	Х	Х	Х	Н

- (1) When used as a single device, PAROE must be tied high.
- (2) Valid after appropriate number of clock pulses have set internal register

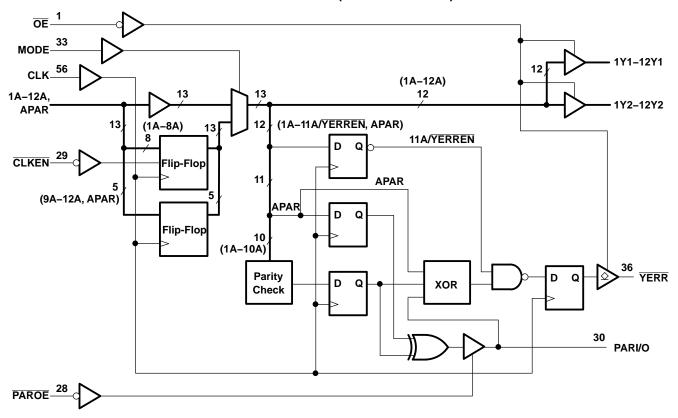
PARI/O FUNCTION(1)

	INPUTS		OUTPUT
PAROE	Σ OF INPUTS 1A-10A = H	APAR	PARI/O
L	0, 2, 4, 6, 8, 10	L	L
L	1, 3, 5, 7, 9	L	Н
L	0, 2, 4, 6, 8, 10	Н	Н
L	1, 3, 5, 7, 9	Н	L
Н	Χ	X	Z

 This table applies to the first device of a cascaded pair of SN74ALVCH16903 devices.



LOGIC DIAGRAM (POSITIVE LOGIC)







ABSOLUTE MAXIMUM RATINGS(1)

over operating free-air temperature range (unless otherwise noted)

			MIN	MAX	UNIT
V_{CC}	Supply voltage range		-0.5	4.6	V
V_{I}	Input voltage range ⁽²⁾	-0.5	4.6	V	
Vo	Output voltage range ⁽²⁾⁽³⁾		-0.5	$V_{CC} + 0.5$	V
I _{IK}	Input clamp current	V _I < 0		-50	mA
I _{OK}	Output clamp current	V _O < 0		-50	mA
Io	Continuous output current			±50	mA
	Continuous current through each V _{CC} or GN	ID		±100	mA
		DGG package		81	
θ_{JA}	Package thermal impedance (4)	DGV package		86	°C/W
		DL package		74	
T _{stg}	Storage temperature range		-65	150	°C

⁽¹⁾ Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

RECOMMENDED OPERATING CONDITIONS(1)

				MIN	MAX	UNIT
V _{CC}	Supply voltage			2.3	3.6	V
\/	High lavel inner contract	$V_{CC} = 2.3 \text{ V to } 2.7 \text{ V}$		1.7		V
V_{IH}	High-level input voltage	$V_{CC} = 2.7 \text{ V to } 3.6 \text{ V}$	V _{CC} = 2.7 V to 3.6 V			V
V	Low lovel input voltage	V _{CC} = 2.3 V to 2.7 V			0.7	V
V_{IL}	Low-level input voltage	$V_{CC} = 2.7 \text{ V to } 3.6 \text{ V}$			0.8	V
VI	Input voltage			0	V _{CC}	V
Vo	Output voltage			0	V _{CC}	V
		$V_{CC} = 2.3 \text{ V}$			-12	
	High lovel output current	$V_{CC} = 2.7 \text{ V}$	r poit		-12	mA
I _{OH}	High-level output current	V _{CC} = 3 V	PARI/O		-12	IIIA
		v _{CC} = 3 v	Y port		-24	
		V _{CC} = 2.3 V	Y port		12	
		$V_{CC} = 2.7 \text{ V}$	r poit		12	
I_{OL}	Low-level output current		PARI/O		12	mA
		$V_{CC} = 3 V$	Y port		24	
			YERR output		24	
$\Delta t/\Delta v$	Input transition rise or fall rate)		0	10	ns/V
T _A	Operating free-air temperatur	e		0	70	°C

All unused control inputs of the device must be held at V_{CC} or GND to ensure proper device operation. Refer to the TI application report, Implications of Slow or Floating CMOS Inputs, literature number SCBA004.

⁽²⁾ The input negative-voltage and output voltage ratings may be exceeded if the input and output current ratings are observed.

This value is limited to 4.6 V maximum.

⁽⁴⁾ The package thermal impedance is calculated in accordance with JESD 51.

SCES095D-MARCH 1997-REVISED SEPTEMBER 2004

ELECTRICAL CHARACTERISTICS

over recommended operating free-air temperature range (unless otherwise noted)

i	PARAMETER	TEST C	CONDITIONS	V _{cc}	MIN	TYP ⁽¹⁾	MAX	UNIT
		I _{OH} = -100 μA		2.3 V to 3.6 V	V _{CC} - 0.2			
		$I_{OH} = -6 \text{ mA},$	V _{IH} = 1.7 V	2.3 V	2			
	V nort		V _{IH} = 1.7 V	2.3 V	1.7			
V_{OH}	Y port	$I_{OH} = -12 \text{ mA}$	V _{IH} = 2 V	2.7 V	2.2			V
			V _{IH} = 2 V	3 V	2.4			
		I _{OH} = -24 mA,	V _{IH} = 2 V	3 V	2			
	PARI/O	$I_{OH} = -12 \text{ mA},$	V _{IH} = 2 V	3 V	2			
		$I_{OL} = 100 \mu A$		2.3 V to 3.6 V			0.2	
		$I_{OL} = 6 \text{ mA},$	V _{IL} = 0.7 V	2.3 V			0.4	
	Y port	1 12 m A	V _{IL} = 0.7 V	2.3 V			0.7	
V_{OL}		I _{OL} = 12 mA	V _{IL} = 0.8 V	2.7 V			0.4	V
		I _{OL} = 24 mA,	V _{IL} = 0.8 V	3 V			0.55	
	PARI/O	$I_{OL} = 12 \text{ mA},$	$V_{IL} = 0.8 \ V$	3 V			0.55	
	YERR output	I _{OL} = 24 mA		3 V			0.5	
I		$V_I = V_{CC}$ or GND		3.6 V			±5	μΑ
		$V_{I} = 0.7 V$		2.3 V	45			
		$V_{I} = 1.7 V$		2.3 V	-45			
I _{I(hold)}		$V_{I} = 0.8 V$		3 V	75			μΑ
		V _I = 2 V		3 V	-75			
		$V_1 = 0$ to 3.6 $V^{(2)}$		3.6 V			±500	
I _{OH}	YERR output	$V_O = V_{CC}$		0 to 3.6 V			±10	μΑ
$I_{OZ}^{(3)}$		$V_O = V_{CC}$ or GND		3.6 V			±10	μΑ
I_{CC}		$V_I = V_{CC}$ or GND,	I _O = 0	3.6 V			40	μΑ
ΔI_{CC}		One input at V _{CC} - 0.6 V,	Other inputs at V _{CC} or GND	3 V to 3.6 V			750	μΑ
C	Control inputs	V – V or CND		3.3 V		5.5		n.E
C _i	Data inputs	$V_I = V_{CC}$ or GND		3.3 V		5.5		pF
C	YERR output	V = V or GND		3.3 V		5		nE.
C _o	Data outputs	$V_0 = V_{CC}$ or GND		3.3 V		6		pF
C _{io}	PARI/O	$V_O = V_{CC}$ or GND		3.3 V		7		pF

All typical values are at V_{CC} = 3.3 V, T_A = 25°C. This is the bus-hold maximum dynamic current. It is the minimum overdrive current required to switch the input from one state to

For I/O ports, the parameter I_{OZ} includes the input leakage current.

SCES095D-MARCH 1997-REVISED SEPTEMBER 2004



TIMING REQUIREMENTS

over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted) (see Figure 1 and Figure 4)

				V _{CC} = 1 ± 0.2		V _{CC} =	2.7 V	V _{CC} = 3 ± 0.3	3.3 V 3 V	UNIT
				MIN	MAX	MIN	MAX	MIN	MAX	
f _{clock}	Clock frequency				125		125		125	MHz
t _w	Pulse duration, 0	CLK↑		3		3		3		ns
		1A-12A before CLK↑	Register mode	1.7		1.9		1.45		
	1A-10A before CLK↑	Buffer mode	5.9		5.2		4.4			
		APAR before CLK↑	Register mode	1.2		1.5		1.3		
t _{su}	Setup time	APAR before CLK	Buffer mode	4.6		3.6		3.1		ns
		PARI/O before CLK↑	Both modes	2.4		2		1.7		
		11A/YERREN before CLK↑	Buffer mode	2		1.9		1.6		
		CLKEN before CLK↑	Register mode	2.5		2.6		2.2		
		1A-12A after CLK↑	Register mode	0.4		0.25		0.55		
		1A-10A after CLK↑	Buffer mode	0.25		0.25		0.25		
		APAR after CLK↑	Register mode	0.7		0.4		0.7		
	llald time	APAR after CLK	Buffer mode	0.25		0.25		0.25		
t _h	Hold time	DADI/O attar CLIV	Register mode	0.25		0.25		0.4		ns
		PARI/O after CLK↑	Buffer mode	0.25		0.25		0.5		
		11A/YERREN after CLK↑	Buffer mode	0.25		0.25		0.4		
		CLKEN after CLK↑	Register mode	0.25		0.5		0.4		

SWITCHING CHARACTERISTICS

over recommended operating free-air temperature range (unless otherwise noted) (see Figure 1 and Figure 4)

Р	ARAMETER	FROM	TO (OUTPUT)	V _{CC} = ± 0.2		V _{CC} =	2.7 V	V _{CC} = 0.3		UNIT
		(INPUT)	(OUTPUT)		MAX	MIN	MAX	MIN	MAX	
f _{max}				125		125		125		MHz
	Buffer mode	А	Y	1	4.4		4.2	1.1	3.8	
t _{pd}	Dath mades	CLIV	YERR	1	5.7		4.9	1.4	4.4	ns
	Both modes	CLK	PARI/O	1.2	8.6		7.9	1.7	6.6	
t _{pd} ⁽¹⁾	Both modes	CLK	PARI/O	1	6.8		5.2	1.3	4.5	ns
t _{pd}	Both modes	MODE	Y	1	5.9		5.8	1.3	4.9	ns
t _{PLH}	De sistem se e de	CLIK	Y	1	6.1		5.5	1.2	4.8	
t _{PHL}	Register mode	CLK	Y	1	5.9		4.9	1.2	4.6	ns
	Dath mades	ŌĒ	Y	1.1	6.5		6.4	1.4	5.4	
t _{en}	Both modes	PAROE	PARI/O	1	5.6		6	1	4.8	ns
	Dath mades	ŌĒ	Y	1	6.4		5.2	1.7	5	
t _{dis}	Both modes	PAROE	PARI/O	1	3.2		3.8	1.2	3.8	ns
t _{PLH}	Doth modes	ŌĒ	VEDD	1	3.6		4.2	1.9	4	
t _{PHL}	Both modes	UE	YERR	1.2	5.1		4.9	1.5	4.2	ns

⁽¹⁾ See Figure 2 and Figure 5 for the load specification.



SCES095D-MARCH 1997-REVISED SEPTEMBER 2004

SIMULTANEOUS SWITCHING CHARACTERISTICS(1)

(see Figure 3 and Figure 6)

PA	RAMETER	FROM (INPUT)	TO (OUTPUT)	V _{CC} = 2.5 V ± 0.2 V		V _{CC} = 2.7 V		V _{CC} = 3.3 V ± 0.3 V		UNIT
		(INFOT)	(001F01)	MIN	MAX	MIN	MAX	MIN	MAX	
t _{PLH}	Dogister mode	CLIK	V	1.8	6.5		6.1	1.8	5	20
t _{PHL}	Register mode	CLK	Ť	1.4	5.9		5.1	1.7	4.5	ns

⁽¹⁾ All outputs switching

OPERATING CHARACTERISTICS FOR BUFFER MODE

 $T_A = 25^{\circ}C$

	PARAMETER	TEST CONDITIONS		V _{CC} = 2.5 V ± 0.2 V	V _{CC} = 3.3 V ± 0.3 V	UNIT	
_	Dower dissination consistence	Outputs enabled	0 0	f 40 MHz	57.5	65	, L
C _{pd}	Power dissipation capacitance	Outputs disabled	$C_L = 0$,	f = 10 MHz	15	17.5	pF

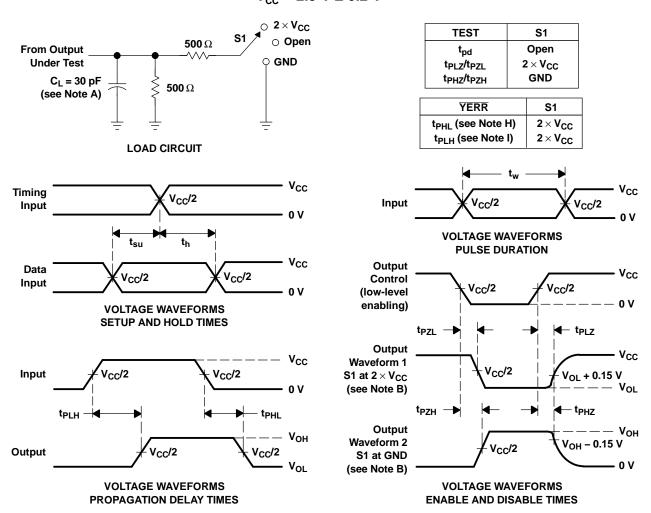
OPERATING CHARACTERISTICS FOR REGISTER MODE

 $T_A = 25^{\circ}C$

PARAMETER Outputs enabled				CONDITIONS	V _{CC} = 2.5 V ± 0.2 V	V _{CC} = 3.3 V ± 0.3 V	UNIT
	Dower dissination consistence	Outputs enabled	C 0	f = 10 MHz	57	87.5	~F
C _{pd}	Power dissipation capacitance	Outputs disabled	$C_L = 0$,	I = 10 WINZ	16.5	34	pF



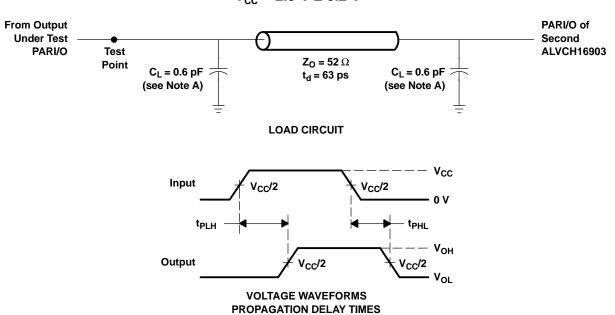
PARAMETER MEASUREMENT INFORMATION V_{cc} = 2.5 V \pm 0.2 V



- NOTES: A. C₁ includes probe and jig capacitance.
 - B. Waveform 1 is for an output with internal conditions such that the output is low, except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high, except when disabled by the output control.
 - C. All input pulses are supplied by generators having the following characteristics: PRR \leq 10 MHz, $Z_O = 50~\Omega$, $t_f \leq$ 2 ns. $t_f \leq$ 2 ns.
 - D. The outputs are measured one at a time, with one transition per measurement.
 - E. t_{PLZ} and t_{PHZ} are the same as t_{dis}.
 - F. t_{PZL} and t_{PZH} are the same as t_{en}.
 - G. t_{PLH} and t_{PHL} are the same as t_{pd}.
 - H. t_{PHL} is measured at $V_{CC}/2$.
 - I. t_{PLH} is measured at V_{OL} + 0.15 V.

Figure 1. Load Circuit and Voltage Waveforms

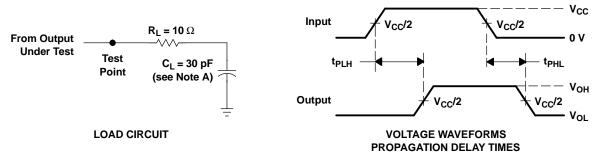
PARAMETER MEASUREMENT INFORMATION $V_{\rm CC}$ = 2.5 V \pm 0.2 V



NOTES: A. C_L includes probe and jig capacitance.

- B. All input pulses are supplied by generators having the following characteristics: PRR \leq 10 MHz, $Z_O = 50~\Omega$, $t_f \leq$ 2 ns, $t_f \leq$ 2 ns.
- C. t_{PLH} and t_{PHL} are the same as t_{pd}.

Figure 2. Load Circuit and Voltage Waveforms



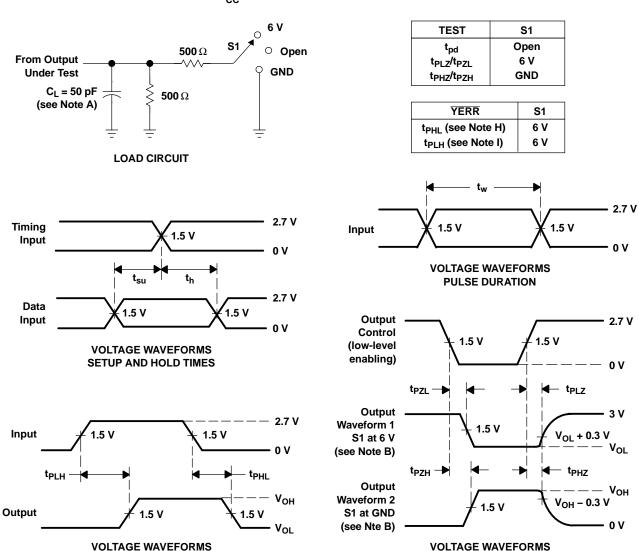
NOTES: A. C_L includes probe and jig capacitance.

B. All input pulses are supplied by generators having the following characteristics: PRR \leq 10 MHz, Z_O = 50 Ω , $t_f \leq$ 2 ns.

Figure 3. Load Circuit and Voltage Waveforms



PARAMETER MEASUREMENT INFORMATION V_{CC} = 2.7 V AND 3.3 V \pm 0.3 V



NOTES: A. C_L includes probe and jig capacitance.

- B. Waveform 1 is for an output with internal conditions such that the output is low, except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high, except when disabled by the output control.
- C. All input pulses are supplied by generators having the following characteristics: PRR \leq 10 MHz, Z_{O} = 50 Ω , $t_{f} \leq$ 2.5 ns, $t_{f} \leq$ 2.5 ns.

ENABLE AND DISABLE TIMES

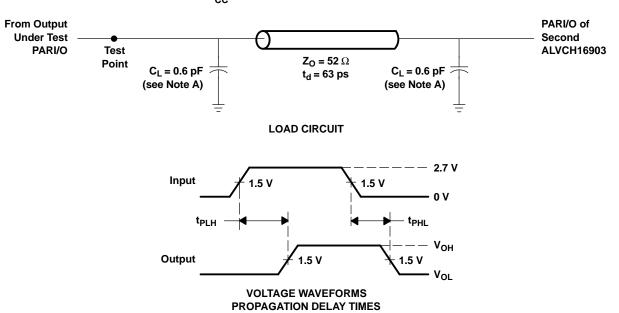
- D. The outputs are measured one at a time, with one transition per measurement.
- E. t_{PLZ} and t_{PHZ} are the same as t_{dis} .

PROPAGATION DELAY TIMES

- F. t_{PZL} and t_{PZH} are the same as t_{en}.
- G. t_{PLH} and t_{PHL} are the same as t_{pd}.
- H. t_{PHL} is measured at 1.5 V.
- I. t_{PLH} is measured at V_{OL} + 0.3 V.

Figure 4. Load Circuit and Voltage Waveforms

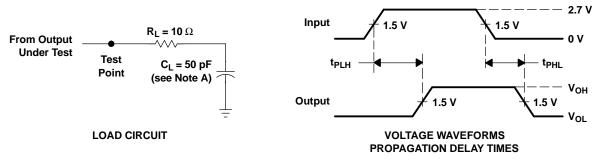
PARAMETER MEASUREMENT INFORMATION V_{CC} = 2.7 V AND 3.3 V \pm 0.3 V



NOTES: A. C_L includes probe and jig capacitance.

- B. All input pulses are supplied by generators having the following characteristics: PRR \leq 10 MHz, $Z_{O} = 50 \Omega$, $t_{f} \leq$ 2.5 ns, $t_{f} \leq$ 2.5 ns.
- C. t_{PLH} and t_{PHL} are the same as t_{pd}.

Figure 5. Load Circuit and Voltage Waveforms



NOTES: A. C_L includes probe and jig capacitance.

B. All input pulses are supplied by generators having the following characteristics: PRR \leq 10 MHz, $Z_O = 50 \Omega$, $t_f \leq$ 2.5 ns. $t_f \leq$ 2.5 ns.

Figure 6. Load Circuit and Voltage Waveforms

www.ti.com 23-May-2025

PACKAGING INFORMATION

Orderable part number	Status (1)	Material type	Package Pins	Package qty Carrier	RoHS	Lead finish/ Ball material	MSL rating/ Peak reflow	Op temp (°C)	Part marking (6)
SN74ALVCH16903DL	Active	Production	SSOP (DL) 56	20 TUBE	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	ALVCH16903
SN74ALVCH16903DL.B	Active	Production	SSOP (DL) 56	20 TUBE	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	ALVCH16903

⁽¹⁾ Status: For more details on status, see our product life cycle.

Multiple part markings will be inside parentheses. Only one part marking contained in parentheses and separated by a "~" will appear on a part. If a line is indented then it is a continuation of the previous line and the two combined represent the entire part marking for that device.

Important Information and Disclaimer: The information provided on this page represents TI's knowledge and belief as of the date that it is provided. TI bases its knowledge and belief on information provided by third parties, and makes no representation or warranty as to the accuracy of such information. Efforts are underway to better integrate information from third parties. TI has taken and continues to take reasonable steps to provide representative and accurate information but may not have conducted destructive testing or chemical analysis on incoming materials and chemicals. TI and TI suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.

In no event shall TI's liability arising out of such information exceed the total purchase price of the TI part(s) at issue in this document sold by TI to Customer on an annual basis.

⁽²⁾ Material type: When designated, preproduction parts are prototypes/experimental devices, and are not yet approved or released for full production. Testing and final process, including without limitation quality assurance, reliability performance testing, and/or process qualification, may not yet be complete, and this item is subject to further changes or possible discontinuation. If available for ordering, purchases will be subject to an additional waiver at checkout, and are intended for early internal evaluation purposes only. These items are sold without warranties of any kind.

⁽³⁾ RoHS values: Yes, No, RoHS Exempt. See the TI RoHS Statement for additional information and value definition.

⁽⁴⁾ Lead finish/Ball material: Parts may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

⁽⁵⁾ MSL rating/Peak reflow: The moisture sensitivity level ratings and peak solder (reflow) temperatures. In the event that a part has multiple moisture sensitivity ratings, only the lowest level per JEDEC standards is shown. Refer to the shipping label for the actual reflow temperature that will be used to mount the part to the printed circuit board.

⁽⁶⁾ Part marking: There may be an additional marking, which relates to the logo, the lot trace code information, or the environmental category of the part.

PACKAGE MATERIALS INFORMATION

www.ti.com 23-May-2025

TUBE



*All dimensions are nominal

Device	Package Name	Package Type	Pins	SPQ	L (mm)	W (mm)	T (µm)	B (mm)
SN74ALVCH16903DL	DL	SSOP	56	20	473.7	14.24	5110	7.87
SN74ALVCH16903DL.B	DL	SSOP	56	20	473.7	14.24	5110	7.87

DL (R-PDSO-G56)

PLASTIC SMALL-OUTLINE PACKAGE



NOTES:

- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion not to exceed 0.006 (0,15).
- D. Falls within JEDEC MO-118

PowerPAD is a trademark of Texas Instruments.



IMPORTANT NOTICE AND DISCLAIMER

TI PROVIDES TECHNICAL AND RELIABILITY DATA (INCLUDING DATA SHEETS), DESIGN RESOURCES (INCLUDING REFERENCE DESIGNS), APPLICATION OR OTHER DESIGN ADVICE, WEB TOOLS, SAFETY INFORMATION, AND OTHER RESOURCES "AS IS" AND WITH ALL FAULTS, AND DISCLAIMS ALL WARRANTIES, EXPRESS AND IMPLIED, INCLUDING WITHOUT LIMITATION ANY IMPLIED WARRANTIES OF MERCHANTABILITY, FITNESS FOR A PARTICULAR PURPOSE OR NON-INFRINGEMENT OF THIRD PARTY INTELLECTUAL PROPERTY RIGHTS.

These resources are intended for skilled developers designing with TI products. You are solely responsible for (1) selecting the appropriate TI products for your application, (2) designing, validating and testing your application, and (3) ensuring your application meets applicable standards, and any other safety, security, regulatory or other requirements.

These resources are subject to change without notice. TI grants you permission to use these resources only for development of an application that uses the TI products described in the resource. Other reproduction and display of these resources is prohibited. No license is granted to any other TI intellectual property right or to any third party intellectual property right. TI disclaims responsibility for, and you will fully indemnify TI and its representatives against, any claims, damages, costs, losses, and liabilities arising out of your use of these resources.

TI's products are provided subject to TI's Terms of Sale or other applicable terms available either on ti.com or provided in conjunction with such TI products. TI's provision of these resources does not expand or otherwise alter TI's applicable warranties or warranty disclaimers for TI products.

TI objects to and rejects any additional or different terms you may have proposed.

Mailing Address: Texas Instruments, Post Office Box 655303, Dallas, Texas 75265 Copyright © 2025. Texas Instruments Incorporated